

# Product Compliance Declaration

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## Contact Information

**Name** Molex Product Compliance **E-Mail** Product.Compliance@molex.com

## Part Information

**Part Number** 0353630352 **Part Weight** 0.27534G

**Part Name** 2.0 W/B CONN.WAFER ASSY

## Product Composition

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
2.0 W/B CONN.WAFER ASSY	Assembly		100	0.27534
20 WB Wafer RA 3P	Component		73.0007	0.201
PHANTOM NO. PLASTIC ( 899920598-RED)	Material		73.0007	0.201
PA66-GF20	Material		73.0007	0.201
PA66	Substance		39.4204	0.10854
GF-Fibre	Substance		14.6001	0.0402
Flame Retardant, ISO 1043-4 FR(17)	Substance		12.4101	0.03417
Antimonytrioxide	Substance	1309-64-4	5.11	0.01407
Further Additives, not to declare	Substance	system	1.46	0.00402
SQ Loose Pin Plated_mm	Component		26.9993	0.07434
Brass C2700	Material		26.923	0.07413
Copper	Substance	7440-50-8	17.8705	0.049205
Lead	Substance	7439-92-1	0.008	0.000022

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Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Iron	Substance	7439-89-6	0.008	0.000022
Zinc (metal)	Substance	7440-66-6	9.0365	0.024881
Electro Tin Plating	Material		0.0327	0.00009
Tin	Substance	7440-31-5	0.0327	0.00009
Electro Copper Plating	Material		0.0436	0.00012
Copper	Substance	7440-50-8	0.0436	0.00012

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## GADSL Declaration Information

**Regulatory Revision** GADSL imported from IMDS

### Contained Substances Exceeding Threshold

Not reviewed

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## ROHS Declaration Information

**Regulatory Revision** EU 2015/863

**Compliance Status** Compliant

### Contained Substances Exceeding Threshold

None

### Exemptions

None

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## REACH-SVHC Declaration Information

**Regulatory Revision** D(2020)9139-DC (19 Jan 2021)

### Contained Substances Exceeding Threshold

None

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## HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

### Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Bromine and its compounds	PA66-GF20	900	170,000	Yes
Bromine and Chlorine combined	PA66-GF20	1,500	170,000	Yes

### China ROHS Declaration Information

Part Number 0353630352		<b>Hazardous Substances</b>				
Part Name 2.0 W/B CONN.WAFER ASSY						
Part Information						
Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
2.0 W/B CONN.WAFER ASSY	○	○	○	○	○	○
20 WB Wafer RA 3P	○	○	○	○	○	○
SQ Loose Pin Plated_mm	○	○	○	○	○	○

### Process Information

Component Plating / Surface Finish	MSn
Termination Base Alloy	Brass
Solder Alloy	SnAgCu
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

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